

UL Product iQ™



ZPMV2.E143060 - Wiring, Printed - Component

Wiring, Printed - Component

KSG GmbH

AUERBACHER STR 3-5

GORNSDORF, 09390 Germany

E143060

Type	Cond Width		Max				Max				Meets C	I	
	Min	Cond	SS/	Area	Solder	Assembly		Oper	UL796				
	Min	Edge	Thk	DS/	Diam	Limits	Process			Temp			Class
	mm(in)	mm(in)	mic	DSO	mm	°C	sec	°C		Cycles			
Multilayer (Mass-laminated) printed wiring boards													
MLM	0.15 (0.006)	0.15 (0.006)	30.5 (1.2)	DS	91.4 (3.6)	250	8	-	-	100	V-0	-	-
Multilayer printed wiring boards													
4L	0.04 (0.002)	0.06 (0.002)	9 (0.35)	DS	50.8 (2)	288	20	-	-	130	V-1	All	*
4M	0.04 (0.002)	0.06 (0.002)	9 (0.35)	DS	50.8 (2)	288	20	-	-	130	V-0	All	*
H2 @	0.039 (0.002)	0.117 (0.005)	64 (2.52)	DS	25.4 (1)	288	10	-	-	130	V-0	All	3
M2	0.064 (0.003)	0.10 (0.004)	9 (0.35)	DS	50.0 (2)	288	20	-	-	130	V-0	All	*
M4	0.064 (0.003)	0.10 (0.004)	9 (0.35)	DS	127.0 (5)	288	20	-	-	130	V-0	All	3
M6	0.04 (0.002)	0.06 (0.002)	5 (0.2)	DS	50.8 (2)	-	-	260	6	130	V-0	All	3
M8	0.075 (0.003)	0.10 (0.004)	17 (0.67)	DS	50.0 (2)	288	20	-	-	130	V-0	All	*
ML	0.064 (0.003)	0.19 (0.007)	18 (0.71)	DS	90.2 (3.6)	270	8	-	-	125	V-0	All	*
ML1	0.064 (0.003)	0.10 (0.004)	9 (0.35)	DS	127.0 (5)	288	20	-	-	125	V-0	All	*




ML2	1.100 (0.043)	1.500 (0.059)	30 (1.18)	DS	89.9 (3.5)	255	8	-	-	125	V-0	All	*
ML3	1.350 (0.053)	1.700 (0.067)	30 (1.18)	DS	90 (3.5)	230	3	-	-	130	V-0	All	*
ML4	0.064 (0.003)	0.100 (0.004)	9 (0.35)	DS	127.0 (5)	288	20	-	-	130	V-0	All	3
ML5	0.064 (0.003)	0.10 (0.004)	9 (0.35)	DS	127.0 (5)	288	20	-	-	130	V-0	All	*
ML6	0.064 (0.003)	0.190 (0.007)	18 (0.71)	DS	90.2 (3.6)	270	8	-	-	130	V-0	All	*
ML7	0.064 (0.003)	0.190 (0.007)	18 (0.71)	DS	13.8 (0.5)	270	8	-	-	130	V-0	All	3
Multilayer rigid flex composite printed wiring boards, flammability only Recognition													
SF1	-	-	-	DS	-	270	10	-	-	-	V-0	-	-
SF1<	-	-	-	DS	-	270	10	-	-	-	V-1	-	-
SF2	-	-	-	DS	-	270	10	-	-	-	V-0	-	-
SF2<	-	-	-	DS	-	270	10	-	-	-	V-0	-	-
SF7	-	-	-	DS	-	270	10	-	-	-	V-0	-	-
SF7<	-	-	-	DS	-	270	10	-	-	-	V-1	-	-
Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions intended for use in flexible-rigid applications - Flammability Only Recognition.													
ML-FR1	-	-	-	DS	-	288	10	-	-	-	V-0	-	-
Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions intended for use in flexible-rigid applications.													
ML-FR (a)	0.07 (0.003)	0.07 (0.003)	17 (0.67)	DS	60 (2.4)	288	10	-	-	105	V-0	-	4
ML-FR (Note 1)	0.07 (0.003)	0.07 (0.003)	17 (0.67)	DS	60 (2.4)	288	10	-	-	105	V-0	-	4
ML-FR (b)	0.07 (0.003)	0.09 (0.004)	17 (0.67)	DS	60 (2.4)	288	10	-	-	105	V-0	-	-
ML-FR (b) (Note 1)	0.07 (0.003)	0.09 (0.004)	17 (0.67)	DS	60 (2.4)	288	10	-	-	105	V-0	-	-
ML-FR2	0.08 (0.003)	0.24 (0.009)	35 (1.38)	SS	60 (2.4)	288	10	-	-	130	V-0	-	2

SF (Note 1)	0.09 (0.004)	0.09 (0.004)	17 (0.67)	DS	60 (2.4)	288	20	-	-	130	V-0	All	3
SF1 (a)	0.09 (0.004)	0.09 (0.004)	17 (0.67)	DS	60.0 (2.4)	288	20	-	-	130	V-0	All	3
Single layer flexible printed wiring boards													
FL	0.1 (0.004)	0.3 (0.012)	17.5 (0.69)	DS	61 (2.4)	250	30	-	-	105	V-0	-	-
Single Layer flexible printed wiring boards, flammability only Recognition													
FL1	-	-	-	DS	-	250	30	-	-	-	V-0	-	-
Single layer printed wiring boards													
5G	0.04 (0.002)	0.06 (0.002)	9 (0.35)	DS	50.8 (2)	288	20	-	-	130	V-1	All	*
5H	0.04 (0.002)	0.06 (0.002)	9 (0.35)	DS	50.8 (2)	288	20	-	-	130	V-0	All	*
D1	0.064 (0.003)	0.10 (0.004)	9 (0.35)	DS	127.0 (5)	288	20	-	-	125	V-0	All	*
D2	0.064 (0.003)	0.100 (0.004)	9 (0.35)	DS	50.0 (2)	288	20	-	-	130	V-0	All	*
D4	0.064 (0.003)	0.100 (0.004)	9 (0.35)	DS	127.0 (5)	288	20	-	-	130	V-0	All	3
D5	0.064 (0.003)	0.10 (0.004)	9 (0.35)	DS	127.0 (5)	288	20	-	-	130	V-0	All	*
DKL, EEL	0.064 (0.003)	0.19 (0.007)	18 (0.71)	DS	90.2 (3.6)	270	8	-	-	125	V-0	All	*
DKL2	0.18 (0.007)	0.53 (0.021)	18.3 (0.72)	DS	25.4 (1)	255	8	-	-	120	V-0	All	*
DKL3	0.083 (0.003)	0.25 (0.01)	18.3 (0.72)	DS	90.1 (3.5)	270	8	-	-	100	V-1	All	0
DKL4	0.064 (0.003)	0.10 (0.004)	9 (0.35)	DS	127.0 (5)	288	20	-	-	130	V-0	All	3
DKL6	0.064 (0.003)	0.19 (0.007)	18 (0.71)	DS	90.2 (3.6)	270	8	-	-	130	V-0	All	*
S6	0.04 (0.002)	0.06 (0.002)	5 (0.2)	DS	50.8 (2)	-	-	260	6	130	V-0	All	3
TF1	0.125 (0.005)	0.190 (0.007)	18 (0.71)	DS	89.9 (3.5)	288	10	-	-	150	V-0	All	0
TF2	0.125 (0.005)	0.190 (0.007)	18 (0.71)	DS	90.1 (3.5)	288	10	-	-	105	V-0	▲	0

TF3	0.16 (0.006)	0.22 (0.009)	18 (0.71)	DS	89.9 (3.5)	288	10	-	-	130	V-0	All	0
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* - CTI marking is optional and may be marked on the printed wiring board.

a - The copper thickness values shown above are for the rigid section. For the flexible section, both internal and external copper are 35 mic only.

Marking: Company name or tradename "K", "KSG" or trademark  ,  ,  ,  , type designation. May be followed by a suffix to denote factory identification or burning test classification.

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